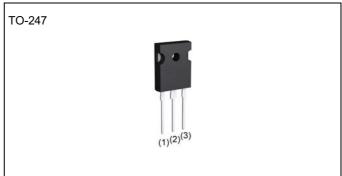
Nch 600V 47A Power MOSFET

| V_{DSS} | 600V |
|----------------------------|------|
| R _{DS(on)} (Max.) | 72mΩ |
| I _D | ±47A |
| P_{D} | 481W |

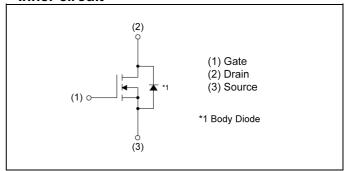
Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

•Inner circuit



Application

Switching

Packaging specifications

| Packing | Tube |
|----------------|-----------|
| Packing code | C13 |
| Marking | R6047KNZ4 |
| Quantity (pcs) | 600 |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit | |
|---|--------------------|--------------------|-------------|----|
| Drain - Source voltage | | V_{DSS} | 600 | V |
| Continuous drain current (T _c = 25 | I _D *1 | ±47 | А | |
| Pulsed drain current | l _{DP} *2 | ±141 | А | |
| 0.1.0 | static | - V _{GSS} | ±20 | V |
| Gate - Source voltage | AC(f>1Hz) | | ±30 | V |
| Avalanche current, single pulse | | I _{AS} | 9.3 | А |
| Avalanche energy, single pulse | | E _{AS} *3 | 1135 | mJ |
| Power dissipation (T _c = 25°C) | P _D | 481 | W | |
| Junction temperature | T _j | 150 | °C | |
| Operating junction and storage te | mperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Downwortow | Cymah al | Values | | | 1.124 |
|--|----------------------|--------|------|------|-------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *4 | - | - | 0.26 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} | - | - | 30 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

• Electrical characteristics $(T_a = 25^{\circ}C)$

| Parameter | Cumb al | Conditions | Values | | | Unit |
|---|--|---|--------|------|------|-------|
| - Farameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$ | | 600 | - | - | V |
| | | V _{DS} = 600V, V _{GS} = 0V | | | | |
| Zero gate voltage drain current | I _{DSS} | $T_j = 25^{\circ}C$ | - | - | 100 | μΑ |
| aram canoni | | $T_j = 125^{\circ}C$ | - | - | 1000 | |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | V _{DS} = 10V, I _D = 1mA | 3.0 | - | 5.0 | V |
| | | V _{GS} = 10V, I _D = 25.8A | | | | |
| Static drain - source on - state resistance | R _{DS(on)} *5 | $T_j = 25^{\circ}C$ | - | 66 | 72 | mΩ |
| | | $T_j = 125^{\circ}C$ | - | - | - | |
| Gate resistance | R_{G} | f = 1MHz, open drain | - | 1.3 | - | Ω |

● Electrical characteristics (T_a = 25°C)

| Daramatar | Cymah al | Conditions | Values | | | Unit |
|------------------------------|--------------------------|---------------------------------------|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 4300 | - | |
| Output capacitance | C _{oss} | V _{DS} = 25V | - | 3700 | - | pF |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 100 | - | |
| Turn - on delay time | t _{d(on)} *5 | $V_{DD} \simeq 300V$, $V_{GS} = 10V$ | - | 55 | - | |
| Rise time | t _r *5 | I _D = 23.5A | - | 155 | - | |
| Turn - off delay time | t _{d(off)} *5 | R _L ~ 12.7Ω | - | 145 | - | ns |
| Fall time | t _f *5 | $R_G = 10\Omega$ | - | 105 | - | |

● Gate charge characteristics (T_a = 25°C)

| Darramatar | Company of | Conditions | Values | | | Lloit |
|----------------------|------------------------|--|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Total gate charge | Q_g^{*5} | V _{DD} ≈ 300V | - | 100 | - | |
| Gate - Source charge | Q _{gs} *5 | I _D = 47A | - | 26 | - | nC |
| Gate - Drain charge | Q _{gd} *5 | V _{GS} = 10V | - | 40 | - | |
| Gate plateau voltage | V _(plateau) | V _{DD} ≈ 300V, I _D = 47A | - | 6.2 | - | V |

^{*1} Limited only by maximum channel temperature allowed

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \rightleftharpoons 20mH, V_{DD}=50V, R_G=25 Ω , Starting T_j=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|-------------------------------|---------------------------|---|--------|------|------|-------|
| - Farameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Source current | I _S *1 | T _C = 25°C | 1 | - | 47 | Α |
| Pulsed source current | I _{SP} *2 | 1C - 23 C | 1 | - | 141 | Α |
| Source-Drain voltage | V _{SD} *5 | $V_{GS} = 0V, I_{S} = 47A$ | - | - | 1.5 | V |
| Reverse recovery time | t _{rr} *5 | | - | 700 | - | ns |
| Reverse recovery charge | Q _{rr} *5 | I _S = 47Α di/dt = 100Α/μs | - | 14 | - | μC |
| Peak reverse recovery current | _{rr} *5 | | - | 40 | - | А |

Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

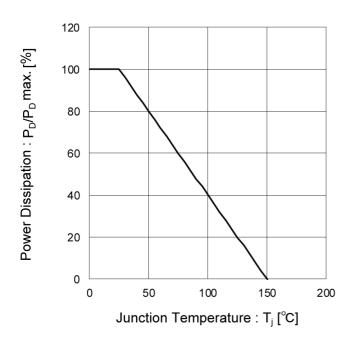


Fig.2 Drain Current Derating Curve

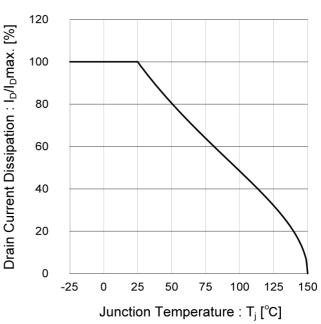


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

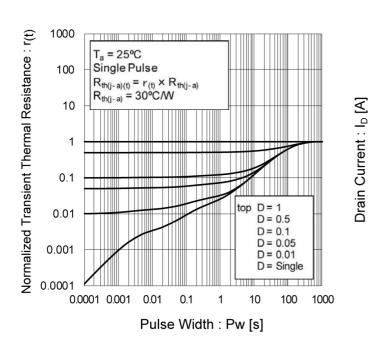
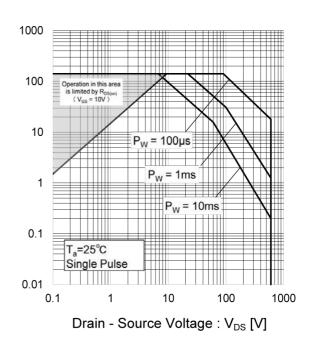


Fig.4 Maximum Safe Operating Area



• Electrical characteristic curves

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

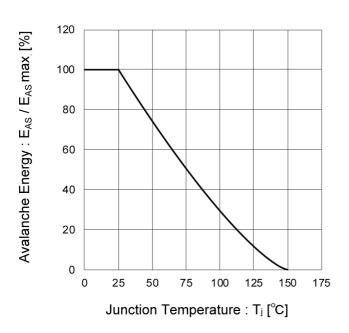


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

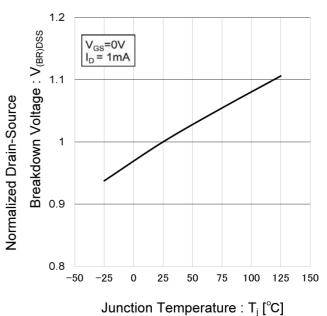


Fig.7 Typical Output Characteristics(I)

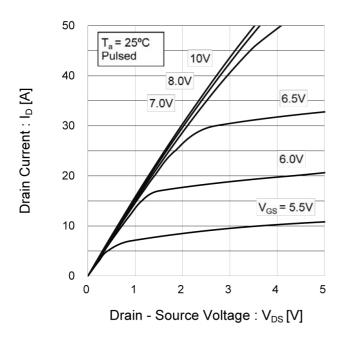
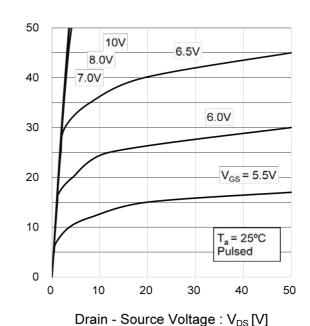


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

• Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

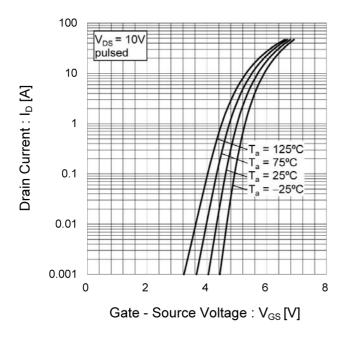
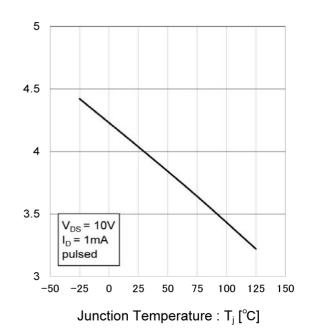


Fig.10 Gate Threshold Voltage vs. Junction Temperature



Gate Threshold Voltage: V_{GS(th)} [V]

Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

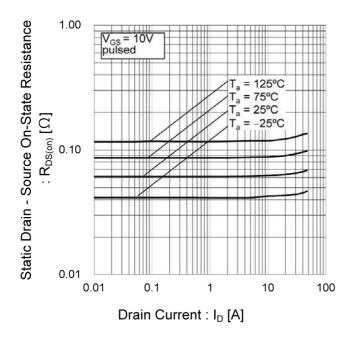
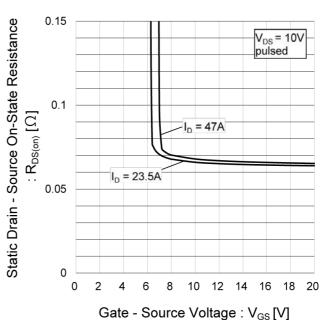


Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage



Electrical characteristic curves

Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

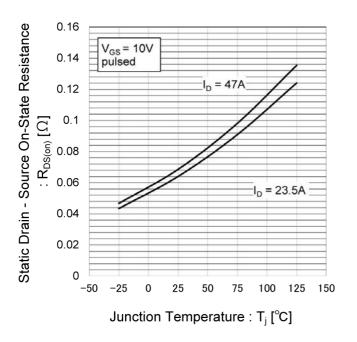


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

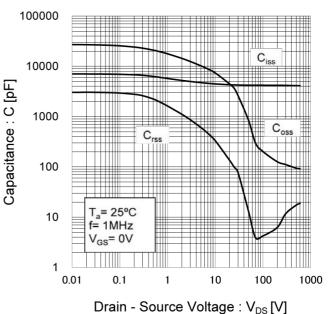


Fig.15 Switching Characteristics

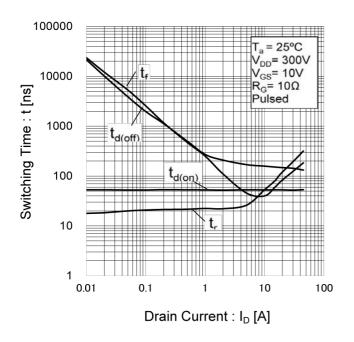
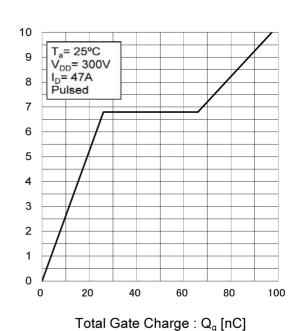


Fig.16 Typical Gate Charge



Gate - Source Voltage : V_{GS} [V]

• Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

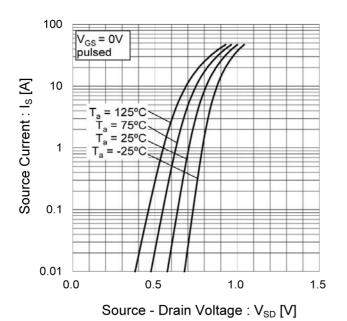
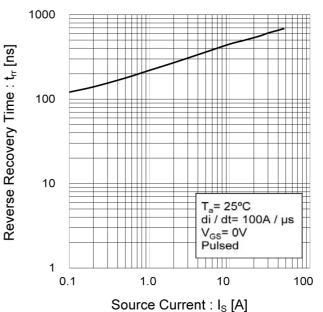


Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

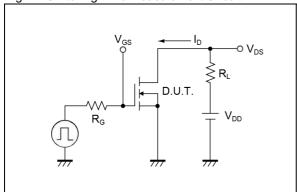


Fig.2-1 Gate Charge Measurement Circuit

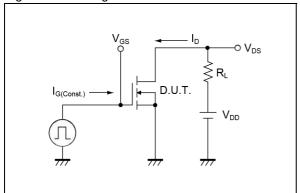


Fig.3-1 Avalanche Measurement Circuit

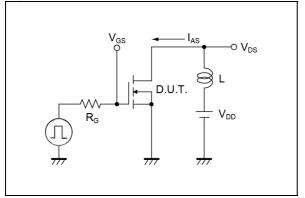


Fig.4-1 trr Measurement Circuit

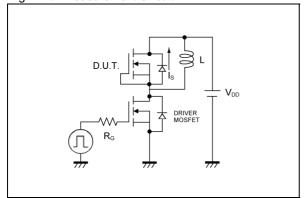


Fig.1-2 Switching Waveforms

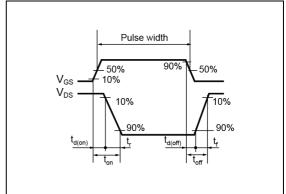


Fig.2-2 Gate Charge Waveform

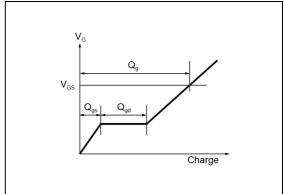


Fig.3-2 Avalanche Waveform

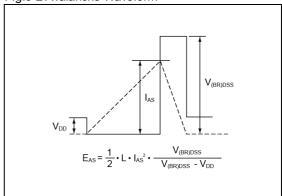
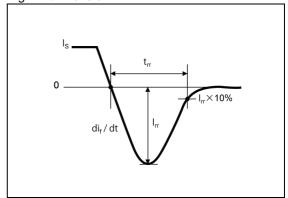
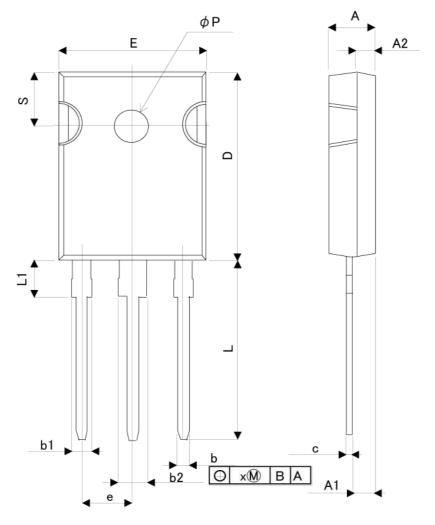


Fig.4-2 trr Waveform



Dimensions

TO-247



| DIM | MILIME | ETERS | INC | HES |
|-------|--------|-------|-------|-------|
| DIIVI | MIN | MAX | MIN | MAX |
| Α | 4.82 | 5.22 | 0.190 | 0.206 |
| A1 | 2.11 | 2.71 | 0.083 | 0.107 |
| A2 | 1.80 | 2.20 | 0.071 | 0.087 |
| b | 1.00 | 1.40 | 0.039 | 0.055 |
| b1 | 1.80 | 2.20 | 0.071 | 0.087 |
| b2 | 2.80 | 3.20 | 0.110 | 0.126 |
| С | 0.45 | 0.75 | 0.018 | 0.030 |
| D | 20.65 | 21.25 | 0.813 | 0.837 |
| E | 15.64 | 16.24 | 0.616 | 0.639 |
| е | 5.4 | 14 | 0.2 | 14 |
| L | 19.77 | 20.37 | 0.778 | 0.802 |
| L1 | 4.09 | 4.29 | 0.161 | 0.169 |
| Р | 3.51 | 3.71 | 0.138 | 0.146 |
| S | 5.97 | 6.37 | 0.235 | 0.251 |

Dimension in mm/inches



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|---------|------------|------------|-----------|
| CLASSⅢ | CL A CC TT | CLASS II b | CL ACCIII |
| CLASSIV | CLASSⅢ | CLASSⅢ | CLASSⅢ |

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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